

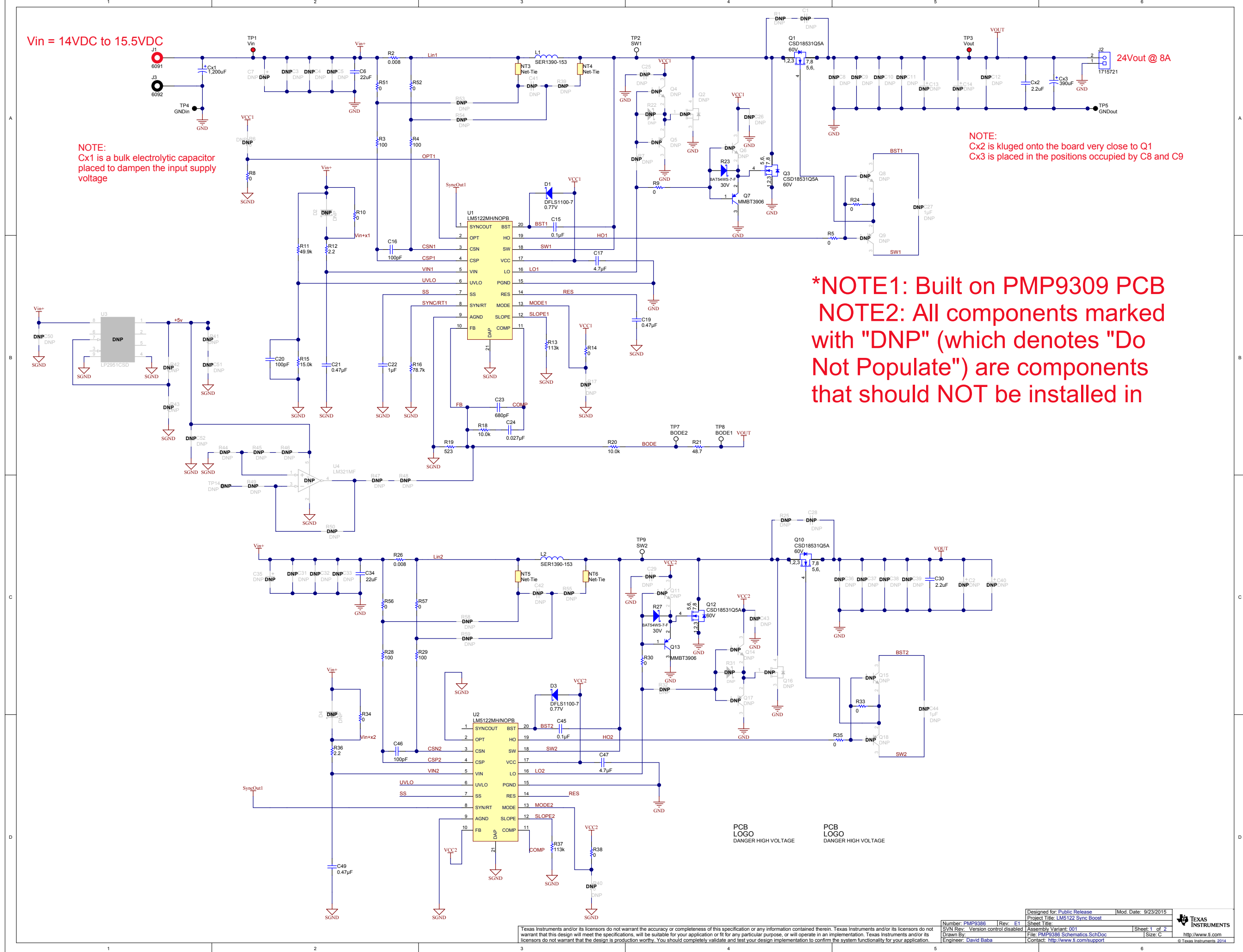
Vin = 14VDC to 15.5VDC

24Vout @ 8A

NOTE:
Cx1 is a bulk electrolytic capacitor placed to dampen the input supply voltage

NOTE:
Cx2 is kluged onto the board very close to Q1
Cx3 is placed in the positions occupied by C8 and C9

*NOTE1: Built on PMP9309 PCB
NOTE2: All components marked with "DNP" (which denotes "Do Not Populate") are components that should NOT be installed in



H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3

PCB: PMP9309 REVC
PMP9309 REVC

PCB LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: Public Release		Mod. Date: 1/16/2015	
Project Title: LM5122 Sync Boost			
Number: PMP9386		Rev: E1	Sheet Title:
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet 2 of 2
Drawn By:		File: PMP9386 Hardware ANSI-B_SchDoc	Size: B
Engineer: David Baba		Contact: http://www.ti.com/support	



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